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(12) **United States Design Patent**
Chang et al.

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- (54) **WAFER CARRIER**
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- (*) Notice: This patent is subject to a terminal disclaimer.
- (**) Term: **14 Years**
- (21) Appl. No.: **29/439,932**
- (22) Filed: **Dec. 17, 2012**

Related U.S. Application Data

- (63) Continuation of application No. 29/385,727, filed on Feb. 18, 2011, now Pat. No. Des. 674,759.
- (51) **LOC (10) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/182**
- (58) **Field of Classification Search**
USPC D13/182; 118/500, 728, 729;
156/345.53; 279/128; 361/234;
451/287, 288, 289
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a wafer carrier, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a wafer carrier showing the claimed design;

FIG. 2 is a front elevational view thereof;

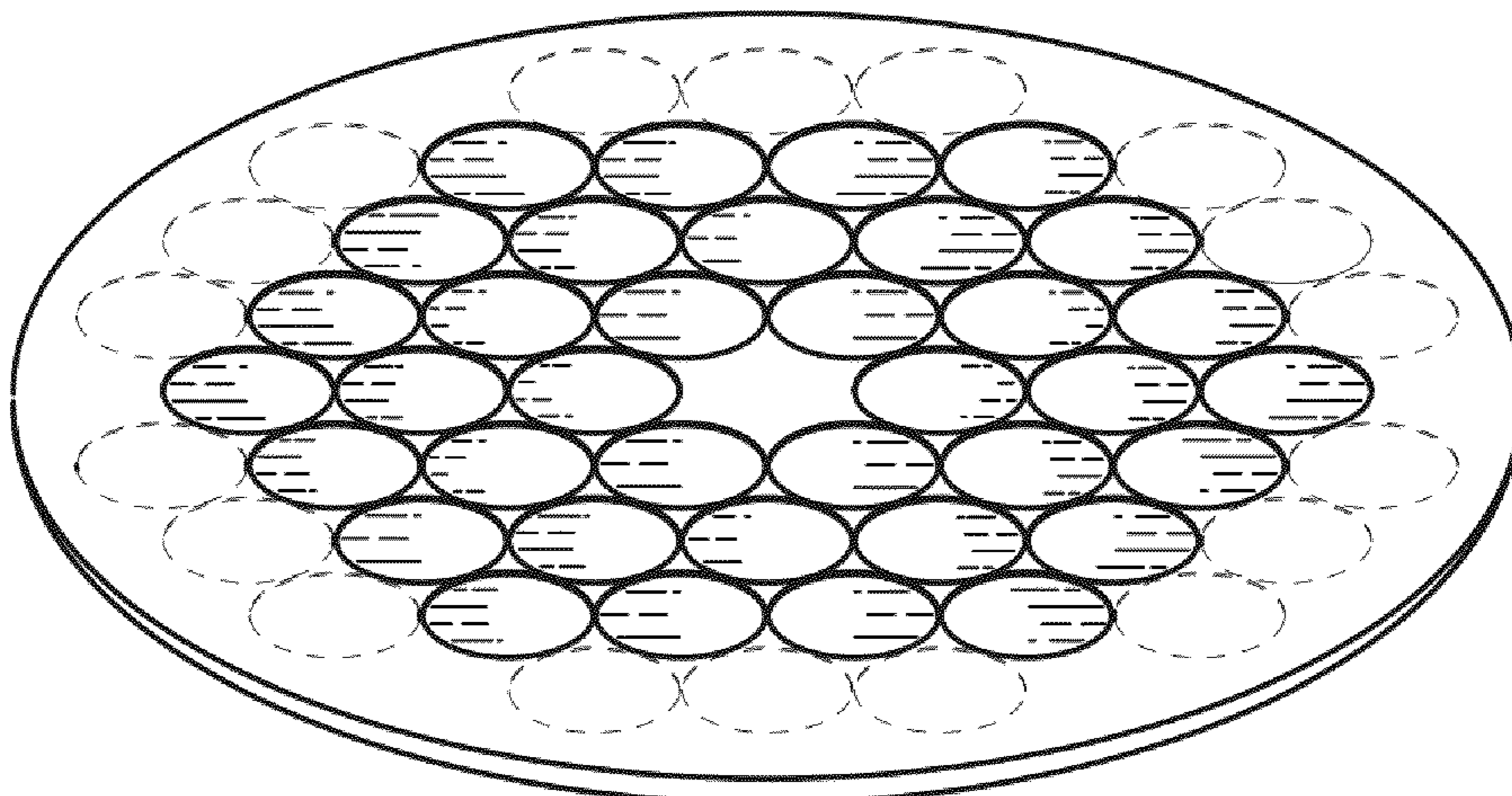
FIG. 3 is a rear elevational view thereof;

FIG. 4 is a right side elevational view thereof, which is a mirror image of the left side elevational view; and,

FIG. 5 is a bottom plan view thereof, which is a mirror image of the top plan view.

The broken lines are directed to environment and are provided for illustrative purpose only; the broken lines form no part of the claimed design.

1 Claim, 5 Drawing Sheets



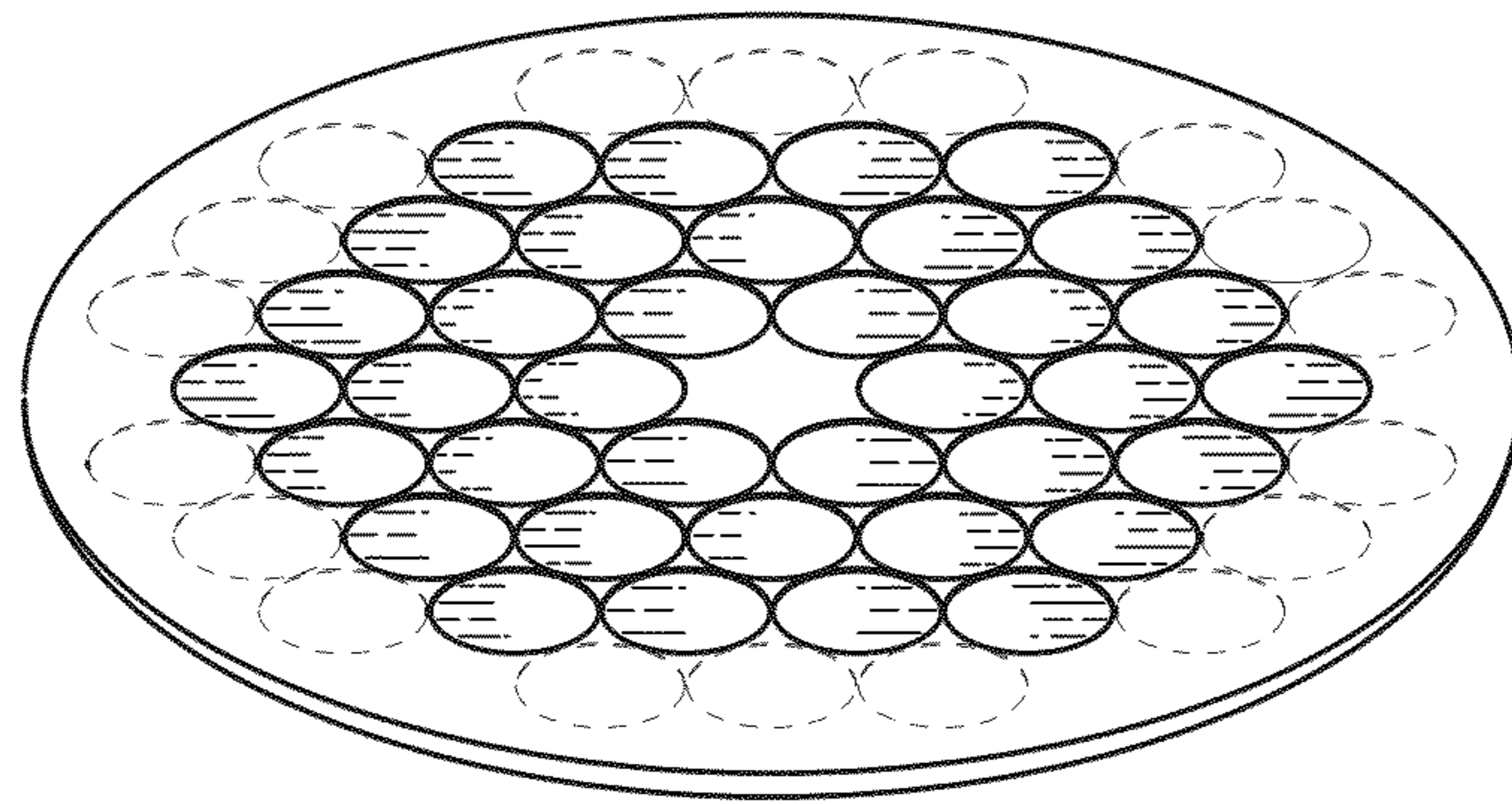


FIG. 1

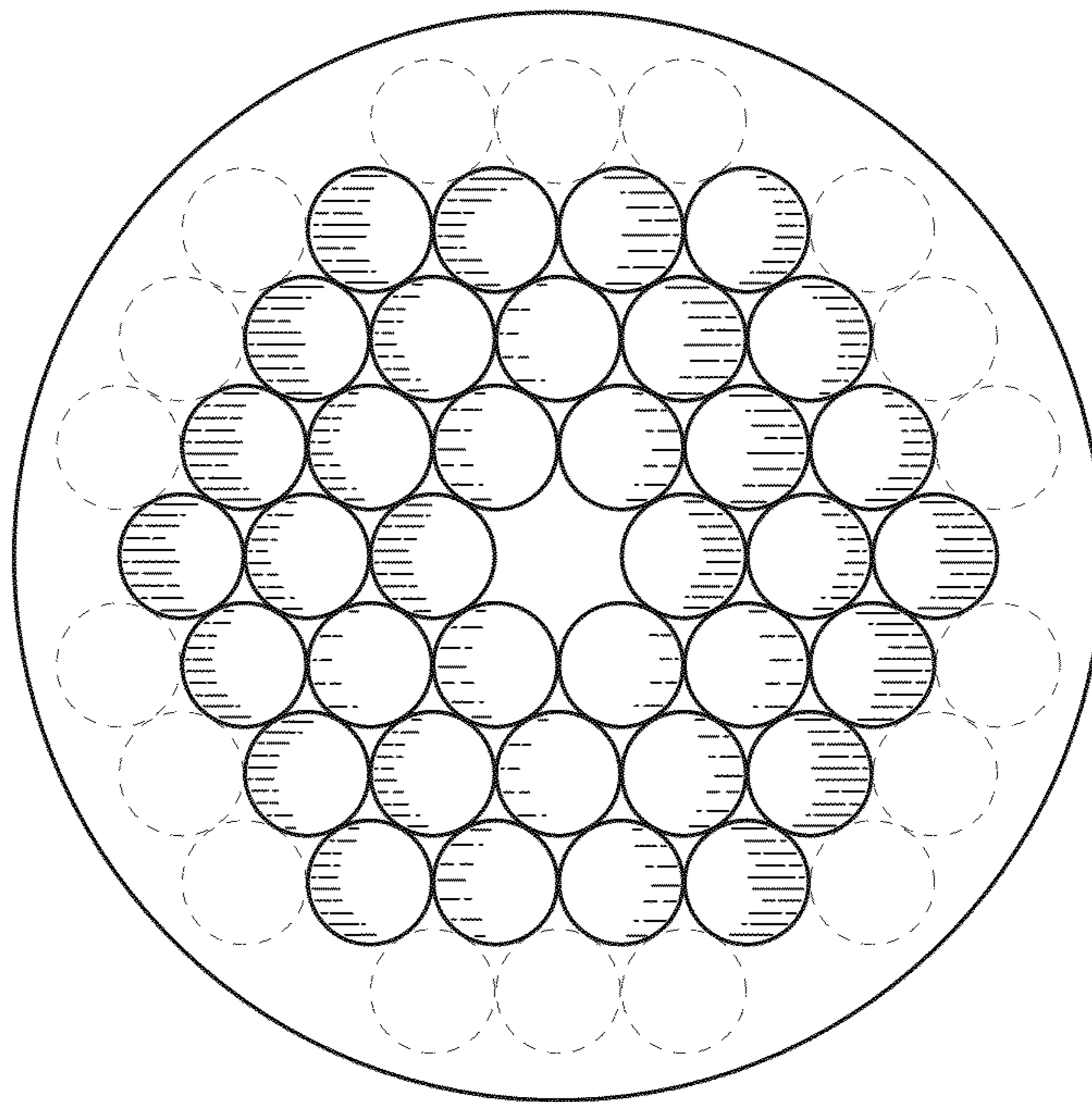


FIG.2

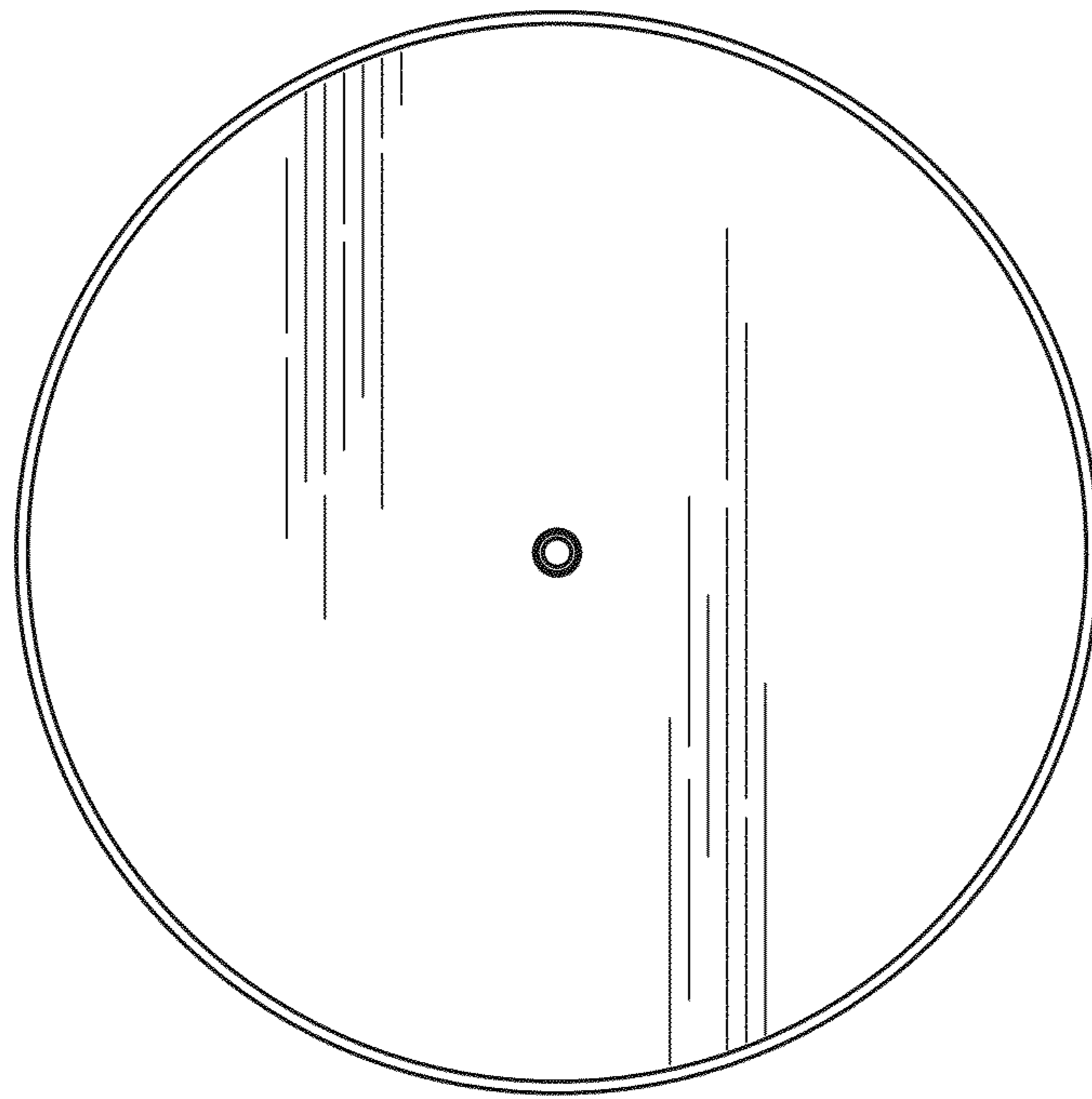


FIG.3



FIG.4



FIG.5